NOTES.
1. PLATING THICKNESS TO BE PER CUSTOMER’S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 0.50 OHMS MAX.

CONTROLED 8-18-03

NAME
40 LEAD SIDE BRAZED PACKAGE

TOlERANCE
S.F AF K.K T.A JUN.23,87

SCALE
1 1

MATERIAL

THIRD ANGLE PROJECTION

KYOCERA CORPORATION
KYOTO JAPAN

DRAWING NO.
KD-S88423-B

SHEET